

INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Not for submission under 37 CFR 1.99)

Application Number	10645047
Filing Date	2003-08-21
First Named Inventor	Sampath Purushothaman et al.
Art Unit	2822
Examiner Name	David E. Graybill
Attorney Docket Number	YOR920030029US2 (16841)

U.S. PATENTS

[Remove](#)

Examiner Initial*	Cite No	Patent Number	Kind Code ¹	Issue Date	Name of Patentee or Applicant of cited Document	Pages, Columns, Lines where Relevant Passages or Relevant Figures Appear
/DG/	1	5081005		1992-01-14	Chakravorty et al.	
/DG/	2	5114754		1992-05-19	Cronin et al.	
/DG/	3	5194928		1993-03-16	Cronin et al.	

If you wish to add additional U.S. Patent citation information please click the Add button.

[Add](#)

U.S. PATENT APPLICATION PUBLICATIONS

[Remove](#)

Examiner Initial*	Cite No	Publication Number	Kind Code ¹	Publication Date	Name of Patentee or Applicant of cited Document	Pages, Columns, Lines where Relevant Passages or Relevant Figures Appear
	1					

If you wish to add additional U.S. Published Application citation information please click the Add button.

[Add](#)

FOREIGN PATENT DOCUMENTS

[Remove](#)

Examiner Initial*	Cite No	Foreign Document Number ³	Country Code ²	Kind Code ⁴	Publication Date	Name of Patentee or Applicant of cited Document	Pages, Columns, Lines where Relevant Passages or Relevant Figures Appear	T ⁵
	1							<input type="checkbox"/>

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**
(Not for submission under 37 CFR 1.99)

Application Number	10645047
Filing Date	2003-08-21
First Named Inventor	Sampath Purushothaman et al.
Art Unit	2822
Examiner Name	David E. Graybill
Attorney Docket Number	YOR920030029US2 (16841)

If you wish to add additional Foreign Patent Document citation information please click the Add button [Add](#)

NON-PATENT LITERATURE DOCUMENTS

[Remove](#)

Examiner Initials*	Cite No	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc), date, pages(s), volume-issue number(s), publisher, city and/or country where published:	T ⁵
/DG/	1	PERFECTO, E. ET AL., Evaluation of Cu Capping Alternatives for Polyimide-Cu MCM-D, Elec. Comp. Tech. Conf., IEEE, 2001	<input type="checkbox"/>
/DG/	2	PRASAD, K. ET AL., Multilevel Thin Film Packaging: Applications and Processes for High Performance Systems, Trans. Comp. Pac. Man. Tech. - Pt. B: Adv. Pac., IEEE, February 1994, pp. 38-49, Vol. 17, No. 1	<input type="checkbox"/>
/DG/	3	SHIH, D.-Y. ET AL., Cu Passivation: A Method of Inhibiting Copper-Polyamic Acid Interactions, Appl. Phys. Lett., September 16, 1991, pp. 1424-1426, Vol. 59, No. 12	<input type="checkbox"/>
/DG/	4	OHUCHI, F. S. ET AL., Summary Abstract: Ti as a Diffusion Barrier Between Cu and Polyimide, J. Vac. Sci. Technol. A, May/June 1988, pp. 1004-1006, Vol. 6, No. 3	<input type="checkbox"/>
/DG/	5	O'SULLIVAN, E. J. ET AL., Electrolessly Deposited Diffusion Barriers for Microelectronics, IBM J. Res. Develop., September 1998, pp. 607-620, Vol. 42, N. 5	<input type="checkbox"/>
/DG/	6	SRINIVASAN, R. ET AL., Ultraviolet Laser Ablation of Organic Polymers, Chem. Rev., 1989, pp. 1303-1316, Vol. 89	<input type="checkbox"/>
/DG/	7	KOWALCZYK, STEVEN P. ET AL., Polyimide on Copper: The Role of Solvent in the Formation of Copper Precipitates, Appl. Phys. Lett., February 1988, pp. 375-376, Vol. 52, No. 5	<input type="checkbox"/>
/DG/	8	KIM, Y.-H. ET AL., Adhesion and Interface Investigation of Polyimide on Metals, J. Adhesion Sci. Technol., 1988, pp. 95-105, Vol. 2, No. 2	<input type="checkbox"/>
/DG/	9	LEE, K.-W. ET AL., Adhesion of Poly(arylene ether benzimidazole) to Copper and Polyimides, J. Adhesion Sci. Technol., 1996, pp. 807-821, Vol. 10, No. 9	<input type="checkbox"/>

**INFORMATION DISCLOSURE
STATEMENT BY APPLICANT**
(Not for submission under 37 CFR 1.99)

Application Number	10645047
Filing Date	2003-08-21
First Named Inventor	Sampath Purushothaman et al.
Art Unit	2822
Examiner Name	David E. Graybill
Attorney Docket Number	YOR920030029US2 (16841)

/DG/	10	MATIENZO, LUIS J. ET AL., Adhesion of Metal Films to Polyimides, IBM Corp., Endicott, NY	<input type="checkbox"/>
/DG/	11	LINDE, H. G., Adhesive Interface Interactions Between Primary Aliphatic Amine Surface Conditioners and Polyamic Acid/Polyimide Resins, J. Poly. Sci.: Poly. Chem. Ed., 1982, pp. 1031-1041, Vol. 20	<input type="checkbox"/>

If you wish to add additional non-patent literature document citation information please click the Add button

EXAMINER SIGNATURE

Examiner Signature	/David E. Graybill/	Date Considered	05/08/2007
--------------------	---------------------	-----------------	------------

*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through a citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

¹ See Kind Codes of USPTO Patent Documents at www.USPTO.GOV or MPEP 901.04. ² Enter office that issued the document, by the two-letter code (WIPO Standard ST.3). ³ For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. ⁴ Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST.16 if possible. ⁵ Applicant is to place a check mark here if English language translation is attached.